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1.	Name of conveying party(ies): Akira Okazaki ///// / 0 /	2.	Name and address of receiving party(ies): Name: Daicel Chemical Industries, Ltd. Address: 1, Teppocho, Sakai-shi Osaka 590-0905 Japan
	Additional name(s) of conveying party(ies) attached? Yes No		Additional name(s) & addresses attached? Yes No
3.	Nature of conveyance:	4.	Patent Application number(s) U.S. Serial No.: 09/890,321; Filed July 27, 2001
	Execution Date(s): September 7, 2001	:	Execution Date(s):
5.	Name and address of party to whom correspondence concerning document should be mailed: Name: Darryl H. Steensma Address: MORGAN & FINNEGAN, L.L.P. 345 Park Avenue New York, NY 10154	7.	Total number of applications involved: 1 Total fee (37 CFR 3.41): \$40.00 ☐ A check in the amount of \$40.00 is enclosed. ☐ Charge to Deposit Account No.: 13-4500, Order No. 1776-4066. ☐ Charge any deficiencies to Deposit Account 13-4500, Order No. 1776-4066. (A duplicate copy of this sheet is enclosed)
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8.	Statement and signature. To the best of my knowledge and belief, the foregoing true copy of original document.	; infor	mation is true and correct and any attached copy is a Date:
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PATENT REEL: 012285 FRAME: 0119

		Docket No	1776-4066
			PATENT
		Docket No.	
	ASSIGNMENT OF APPLICATION FOR PATENT		
VHEI	REAS:		
Akira	OKAZAKI, 8-2, Kuba 6-chome, Ohtake-shi, Hiroshima, 739-0651 Japan		
			We will control of
			(
full na	ame(s) and post office address(s) of inventor(s) (including country))		
herein	nafter referred to as ASSIGNOR(S)), has made a discovery or invention entitled:		
	CTIVE MONOMER COMPOSITION MODIFIED BY A SMALL-AMOUNT COLUMN RESIN, A CURABLE RESIN COMPOSITION, AND A COATING COMP		S, AN ACRYLIC
itle of	f discovery or invention)		
X]	for which application for Letters Patent of the United States has been executed on ever	en date herewith,	
]	for which application for Letters Patent of the United States has been filed onand	_, under Serial N	lo
WHE	REAS:		
DAIC	EL CHEMICAL INDUSTRIES, LTD., 1, Teppocho, Sakai-shi, Osaka 590-0905 J	apan	
name	and address of assignee)		
(herei Letter	nafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and unc s Patent or similar legal protection to be obtained therefor in the United States and in any	ler said invention and all foreign o	and in, to and under countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR(S) of the sum of ONE Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR(S) hereby sells, assigns and transfers to ASSIGNEE, its successors, legal representatives and assigns, the full and exclusive right, title and interest to said discovery or invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the

Docket No. __1776-4066

United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in a foreign country for the full term or terms for which the same may be granted.

I, SAID ASSIGNOR(S), hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and any Official of any country or countries foreign to the United States of America whose duty it is to issue Letters Patent on applications as aforesaid, to issue all such Letters Patent for said discovery or invention to the ASSIGNEE, as assignee of the entire right, title and interest in, to and under the same, for the sole use and behalf of the ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

I, SAID, ASSIGNOR(S), hereby covenant that I have full right to convey the entire right, title and interest herein sold, assigned, transferred and set over;

AND I, SAID ASSIGNOR(S) hereby further covenant and agree that the ASSIGNEE, its successors, legal representatives, or assigns, may apply for foreign Letters Patent on said discovery or invention and claim the benefits of the International Convention, and that I will, at any time, when called upon to do so by the ASSIGNEE, its successors, legal representatives, or assigns, communicate to the ASSIGNEE, its successors, legal representatives, or assigns, as the case may be, any facts known to me respecting said discovery or invention, and execute and deliver any and all lawful papers that may be necessary or desireable to perfect the title to the said discovery or invention, the said applications and the said Letters Patent in the ASSIGNEE, its successors, legal representatives and assigns, and that if reissues of the said Letters Patent or disclaimers relating thereto, or divisions, continuations, or refilings of the said applications, or any thereof, shall hereafter be desired by the ASSIGNEE, its successors, legal representatives, or assigns, I will, at any time, when called up to do so by the ASSIGNEE, its successors, legal representatives, or assigns sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all divisional, continuation and reissue applications so desired, and do all lawful acts requisite for the application for such reissues and the procuring thereof and for the filing of such disclaimers and such applications, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention or discover in all countries, and without further compensation but at the expense of the ASSIGNEE, its successors, legal representatives and assigns.

	Ohim		Coping area	
Assignor's signature:	First Name	Middle initial	Last name	
Citizenship: Japan			7 ch down September 2001.	
IN WITNESS WHERE	OF, I have hereunto set 1	my hand and affixed my seal this	7 ch day of Septenber, 2001.	
STATE OF) ss.:			
COUNTY OF)			
On this day of _		, before me, the undersigned author		
known and known to acknowledged to me th	me to be the individual nat he executed the same	who is described in and who e as his own voluntary act and dee	executed the foregoing Assignment, and who dured for the uses and purposed therein specified.	ıly

Notary Public

FORM: ASSIGN. PAT

Rev. 07/29/99

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RECORDED: 10/12/2001

PATENT REEL: 012285 FRAME: 0122